

CLAIM AMENDMENTS

1. (Currently Amended) A method of polishing or planarizing a substrate comprising abrading at least a portion of the surface of a substrate comprising tungsten with a composition comprising a silica abrasive and a liquid carrier, wherein the composition has a pH of ~~[[4-6]]~~ about 7 or less and the silica abrasive has a total surface hydroxyl group density no greater than about 3 hydroxyl groups per nm².

2.-16. (Canceled)

17. (Previously Presented) The method of claim 1, wherein the silica abrasive is fumed silica.

18. (Previously Presented) The method of claim 1, wherein the total surface hydroxyl group density is no greater than about 2.8 hydroxyl groups per nm².

19. (Previously Presented) The method of claim 18, wherein the total surface hydroxyl group density is no greater than about 2.5 hydroxyl groups per nm².

20. (Previously Presented) The method of claim 1, wherein the substrate further comprises a metal oxide.

21. (Previously Presented) The method of claim 20, wherein the metal oxide of the substrate is selected from the group consisting of alumina, titania, ceria, zirconia, germania, magnesia, and combinations thereof.

22. (Previously Presented) The method of claim 20, wherein the metal oxide of the substrate is silica.

23. (Previously Presented) The method of claim 1, wherein the substrate further comprises a metal composite.

24. (Previously Presented) The method of claim 23, wherein the metal composite of the substrate is titanium nitride, tungsten nitride, and nickel-phosphorus.

In re Appln. of Dirksen et al.
Application No. 09/737,905

25. (New) The method of claim 1, wherein the composition has a pH of 4-6.